

P54/74FCT273/A/C (P54/74PCT273/A/C) OCTAL D FLIP-FLOP

★ FEATURES

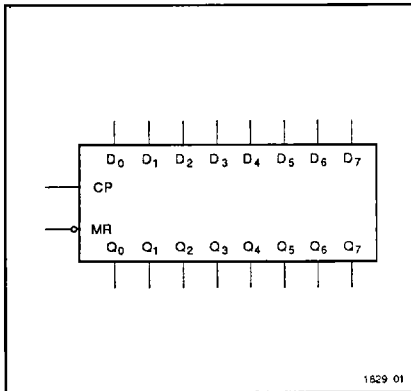
- Function, Pinout, and Drive Compatible with the FCT and F Logic
- FCT-C speed at 5.8ns max. (Com'I)
FCT-A speed at 7.2ns max. (Com'I)
- CMOS V_{OH} Levels for Low Power Consumption
— Typically 1/3 of FAST Bipolar Logic
- Edge-rate Control Circuitry for Significantly Improved Noise Characteristics
- ESD protection exceeds 2000V
- Inputs and Outputs Interface Directly with TTL, NMOS, and CMOS Devices
- Outputs Meet Levels Required for CMOS Static RAM Low Power Standby Mode
- 64 mA Sink Current (Com'I), 48 mA (MII)
15 mA Source Current (Com'I), 12 mA (MII)
- Edge Triggered D Flip-Flops
- 250MHz Typical Toggle Rate
- Buffered Common Clock
- Buffered, Asynchronous Master Reset
- Input Clamp Diode to Limit Bus Reflections
- Manufactured in 0.8 micron PACE Technology™

★ DESCRIPTION

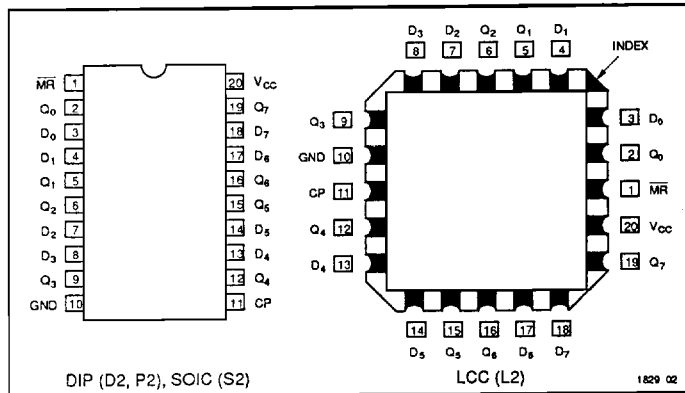
The 'FCT273 consists of eight edge triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered clock (CP) and master reset (MR) load and reset (clear) all flip-flops simultaneously. The 'FCT273 is an

edge triggered register. The state of each D input (one setup time before the low-to-high clock transition) is transferred to the corresponding flip-flop's Q output. All outputs will be forced low by a low voltage level on the MR input.

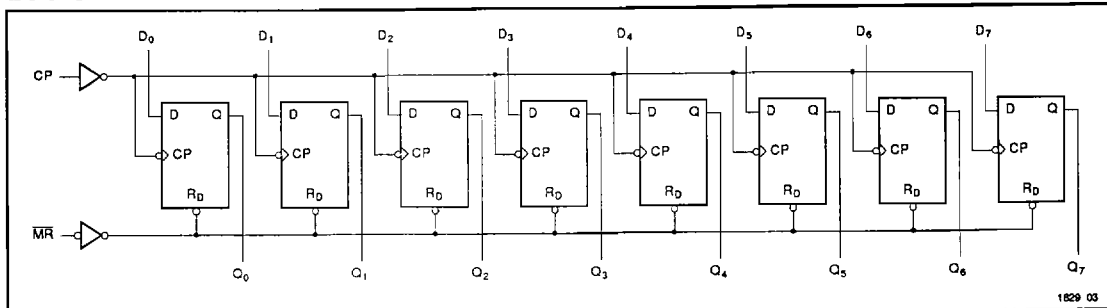
★ LOGIC SYMBOL



PIN CONFIGURATIONS



LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS^{1,2}

Symbol	Parameter	Value	Unit
T_{STG}	Storage Temperature	-65 to +150	°C
T_A	Ambient Temperature Under Bias	-55 to +125	°C
V_{CC}	V_{CC} Potential to Ground	-0.5 to +7.0	V
I_{IN}	Input Current	-30 to +5.0	mA

Notes:

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1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

Symbol	Parameter	Value	Unit
I_{OUTPUT}	Current Applied to Output	100	mA
V_{IN}	Input Voltage	-0.5 to $V_{CC} + 0.5$	V
V_{OUT}	Voltage Applied to Output	-0.5 to $V_{CC} + 0.5$	V

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2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.

RECOMMENDED OPERATING CONDITIONS

Free Air Ambient Temperature	Min	Max
Military	-55°C	+125°C
Commercial	0°C	+70°C

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Supply Voltage (V_{CC})	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

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DC ELECTRICAL CHARACTERISTICS (Over recommended operating conditions)

Symbol	Parameter		Min	Typ ¹	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		
V_{IL}	Input LOW Voltage				0.8	V		
V_H	Hysteresis			0.35		V		All inputs
V_{CD}	Input clamp diode voltage				-1.2	V	MIN	$I_{IN} = -18mA$
V_{OH}	Output HIGH voltage	Military	2.4	3.3		V	MIN	$I_{OH} = -12mA$ $I_{OH} = -15mA$
		Commercial						
V_{OL}	Output LOW voltage	Military (TTL)			0.5	V	MIN	$I_{OL} = 32mA$ $I_{OL} = 48mA$
		Commercial (TTL)						
I_{IH}	Input HIGH Current				5	μA	MAX	$V_{IN} = V_{CC}$
I_{IL}	Input LOW Current				-5	μA	MAX	$V_{IN} = GND$
I_{IH}	Input HIGH Current ³				5	μA	MAX	$V_{OUT} = 2.7V$
I_{IL}	Input LOW Current ³				-5	μA	MAX	$V_{OUT} = 0.5V$
I_{OS}	Output short circuit ²		-60			mA	MAX	$V_{OUT} = 0.0V$
C_{IN}	Input capacitance ³			5	10	pF		All inputs
C_{OUT}	Output capacitance ³			9	12	pF		All outputs

Notes:

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1. Typical limits are at $V_{CC} = 5.0V$, $T_A = +25^\circ C$ ambient.
 2. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect

operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

3. This parameter is guaranteed but not tested.

DC CHARACTERISTICS (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ ¹	Max	Units	Conditions	
I_{CC}	Quiescent Power Supply Current (CMOS inputs)	Com'l Mil	0.003 0.003	0.3 0.5	mA mA	$V_{CC} = \text{MAX}, V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V, f = 0,$ Outputs Open
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)		2.0	2.0	mA	$V_{CC} = \text{MAX}, V_{IN} = 3.4V^2,$ $f = 0, \text{Outputs Open}$
I_{CCD}	Dynamic Power Supply Current ³		0.25	0.25	mA/ mHz	$V_{CC} = \text{MAX}, \text{One Bit Toggling},$ 50% Duty Cycle, $MR = V_{CC},$ $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V,$ Outputs Open
I_C	Total Power Supply Current ⁵		4.0	4.0	mA	$V_{CC} = \text{MAX}, f_0 = 10\text{MHz},$ 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 5\text{MHz},$ $MR = V_{CC}$ and $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
			6.0	6.0	mA	$V_{CC} = \text{MAX}, f_0 = 10\text{MHz},$ 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 5\text{MHz},$ $MR = V_{CC}$ and $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$
			7.8 ⁴	7.8 ⁴	mA	$V_{CC} = \text{MAX}, f_0 = 10\text{MHz},$ 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 2.5\text{MHz},$ $MR = V_{CC}$ and $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
			16.8 ⁴	16.8 ⁴	mA	$V_{CC} = \text{MAX}, f_0 = 10\text{MHz},$ 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 2.5\text{MHz},$ $MR = V_{CC}$ and $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$

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Notes:

- Typical values are at $V_{CC} = 5.0V, +25^\circ\text{C}$ ambient and maximum loading.
- Per TTL driven input ($V_{IN} = 3.4V$); all other inputs at V_{CC} or GND.
- This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
- $$I_C = I_{\text{QUIESCENT}} + I_{\text{INPUTS}} + I_{\text{DYNAMIC}}$$

$$I_C = I_{CC} + \Delta I_{CC} D_n N_T + I_{CCD} (f_0/2 + f_1 N_i)$$

$$I_{CC} = \text{Quiescent Current with CMOS input levels}$$

ΔI_{CC} = Power Supply Current for a TTL High Input ($V_{IN} = 3.4V$)

D_n = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_n

I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_0 = Clock Frequency for Register Devices (Zero for Non-Register Devices)

f_1 = Input Frequency

N_i = Number of Inputs at f_1

All currents are in milliamps and all frequencies are in megahertz.

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MODE SELECT-FUNCTION TABLE

Operating Mode	Inputs			Output
	\overline{MR}	CP	D_n	Q_n
Reset (clear)	L	X	X	L
Load '1'	H	$\overline{\text{L}}$	h	H
Load '0'	H	$\overline{\text{L}}$	l	L

H = HIGH Voltage Level steady state

h = HIGH Voltage Level one setup time prior to LOW-to-HIGH clock transition

L = LOW Voltage Level steady state

l = LOW Voltage Level one setup time prior to the LOW-to-HIGH transition

X = Don't Care

$\overline{\text{L}}$ = LOW-to-HIGH clock transition

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AC CHARACTERISTICS

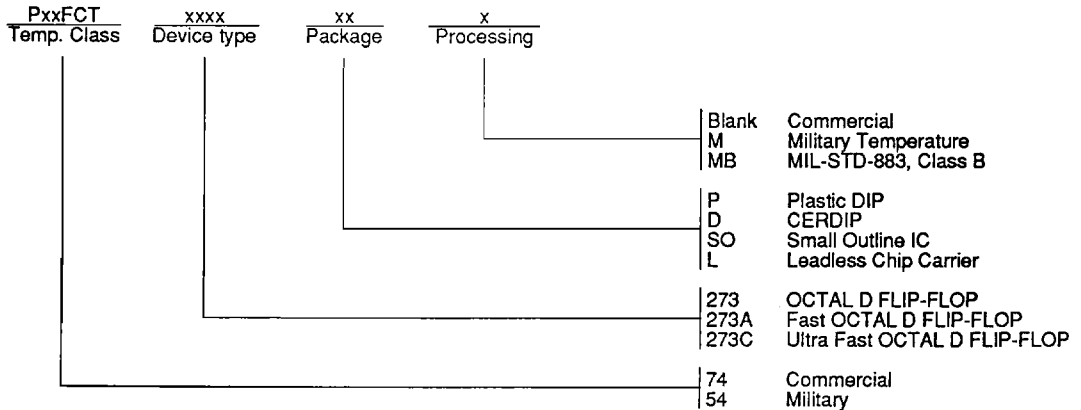
Symbol	Parameter	'FCT273				'FCT273A				'FCT273C				Units	Fig. No.
		MIL		COM'L		MIL		COM'L		MIL		COM'L			
		Min. ¹	Max.	Min.	Max.	Min. ¹	Max.	Min.	Max.	Min. ¹	Max.	Min.	Max.		
t_{PLH} t_{PHL}	Propagation Delay Clock to Output	2.0	10.0	2.0	9.0	2.0	8.3	2.0	7.2	2.0	6.5	2.0	5.8	ns	1, 5
t_{PLH} t_{PHL}	Propagation Delay MR to Output	2.0	12.5	2.0	11.0	2.0	8.3	2.0	7.2	2.0	6.8	2.0	6.1	ns	1, 6
$t_s(H)$ $t_s(L)$	Set-up Time HIGH or LOW D_n to CP	3.0	—	3.0	—	2.0	—	2.0	—	2.0	—	2.0	—	ns	4
$t_h(H)$ $t_h(L)$	Hold Time HIGH or LOW D_n to CP	1.0	—	1.0	—	1.5	—	1.5	—	1.5	—	1.5	—	ns	4
$t_w(H)$ $t_w(L)$	Clock Pulse Width ² HIGH or LOW	7.0	—	6.0	—	6.0	—	6.0	—	6.0	—	6.0	—	ns	5
$t_w(H)$ $t_w(L)$	MR Pulse Width LOW	6.0	—	6.0	—	6.0	—	6.0	—	6.0	—	6.0	—	ns	6
t_{rec}	Recovery Time MR to Clock	3.0	—	3.0	—	2.5	—	2.0	—	2.5	—	2.0	—	ns	6

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Notes:

1. Minimum limits are guaranteed but not tested on Propagation Delays.
2. AC Characteristics guaranteed with $C_L = 50pF$ as shown in Figure 1.

ORDERING INFORMATION



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